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09/916197

Class	Subclass	ISSUE CLASSIFICATION

PATENT NUMBER

JC1
1106

U.S. UTILITY Patent Application

7/15 O.I.P.E. PATENT DATE
 SCANNED Q.A. *Wtd*

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/916197	F	361	707	2841 2707	Vig...

APPLICANTS
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TITLE
 Method for encapsulating intermediate conductive elements connecting a semiconductor die to a substrate and semiconductor devices so packaged

PTO-2040
12/99

ISSUING CLASSIFICATION							
ORIGINAL				CROSS REFERENCE(S)			
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
INTERNATIONAL CLASSIFICATION							

Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____	_____ (Primary Examiner) _____ (Date)			ISSUE FEE	
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)			Amount Due	Date Paid
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